

Paper No. 16

L Number	Hits	Search Text	DB	Time stamp
1	3251	((438/704,706,709,710,711,719,745,753).CCL\$USPAT; US-PGPUB; EPC; JPO; DEFWENT; IBM TIB	2002/06/12 13:16	
2	16	((438/704,706,709,710,711,719,745,753).CCL\$USPAT; and (wet adj etching).ti.	2002/06/12 US-PGPUB; EPC; JPO; DEFWENT; IBM TIB	2002/06/12 13:16
3	5	((438/704,706,709,710,711,719,745,753).CCL\$USPAT; and (wet adj etching).ti.) and plasma	2002/06/12 US-PGPUB; EPC; JPO; DEFWENT; IBM TIB	2002/06/12 13:18
4	5	((438/704,706,709,710,711,719,745,753).CCL\$USPAT; and (wet adj etching).ti.) and plasma) and wet near3 etching	2002/06/12 US-PGPUB; EPC; JPO; DEFWENT; IBM TIB	2002/06/12 13:21
5	2	((438/704,706,709,710,711,719,745,753).CCL\$USPAT; and wet adj etching with substrate with plasma adj etching	2002/06/12 US-PGPUB; EPC; JPO; DEFWENT; IBM TIB	2002/06/12 13:25
6	32	((438/704,706,709,710,711,719,745,753).CCL\$USPAT; and alignment adj mark	2002/06/12 US-PGPUB; EPC; JPO; DEFWENT; IBM TIB	2002/06/12 13:25
7	31	((438/704,706,709,710,711,719,745,753).CCL\$USPAT; and plasma adj etching with wet adj etching	2002/06/12 US-PGPUB; EPC; JPO; DEFWENT; IBM TIB	2002/06/12 13:42
8	25	((438/704,706,709,710,711,719,745,753).CCL\$USPAT; and wet adj etching with advantages	2002/06/12 US-PGPUB; EPC; JPO; DEFWENT; IBM TIB	2002/06/12 13:44
9	13	((438/704,706,709,710,711,719,745,753).CCL\$USPAT; and fine with wet adj etching	2002/06/12 US-PGPUB; EPC; JPO; DEFWENT; IBM TIB	2002/06/12 13:55
10	132	((438/704,706,709,710,711,719,745,753).CCL\$USPAT; and wet adj etching and cost	2002/06/12 US-PGPUB; EPC; JPO; DEFWENT; IBM TIB	2002/06/12 13:55
11	16	((438/704,706,709,710,711,719,745,753).CCL\$USPAT; and wet adj etching and cost) and wet adj etching with plasma	2002/06/12 US-PGPUB; EPC; JPO; DEFWENT; IBM TIB	2002/06/12 14:36
12	2	jp-62018714-\$.did.	2002/06/12 USPAT; US-PGPUB; EPC; JPO; DEFWENT; IBM TIB	2002/06/12 14:36